



## 80V N-Channel SGT Power MOSFET

### General Description

The SJ046N08 uses SGT technology to provide excellent  $R_{DS(ON)}$ , low gate charge and fast switching characteristics. This device is suitable for use as a wide variety of applications.

### Features

- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handling capability
- Lead free product is acquired

### Application

- DC/DC Converter
- Load Switch
- Power Management

### Key Performance Parameters

Parameter	Value	Unit
$V_{DS}$	80	V
$R_{DS(ON\_TYP)}$	4.7	m $\Omega$
$I_D$	120	A
$Q_G$	49	nC



### Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJ046N08	SJ046N08	TO-220	Tube	\	\	1000 Pcs

**Table 1. Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Limit	Unit
$V_{DS}$	Drain-Source Voltage ( $V_{GS}=0\text{V}$ )	80	V
$V_{GS}$	Gate-Source Voltage ( $V_{DS}=0\text{V}$ )	$\pm 20$	V
$I_D$	Drain Current-Continuous( $T_C=25^\circ\text{C}$ )	120	A
	Drain Current-Continuous( $T_C=100^\circ\text{C}$ )	76	A
$I_{DM}$ (pluse)	Drain Current-Continuous@ Current-Pulsed (Note 1)	480	A
$P_D$	Maximum Power Dissipation( $T_C=25^\circ\text{C}$ )	152	W
	Maximum Power Dissipation( $T_C=100^\circ\text{C}$ )	611	W
$E_{AS}$	Avalanche energy (Note 2)	529	mJ
$T_J, T_{STG}$	Operating Junction and Storage Temperature Range	-55 To 150	$^\circ\text{C}$

**Table 2. Thermal Characteristic**

Symbol	Parameter	Typ	Max	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		0.82	$^\circ\text{C/W}$



## 80V N-Channel SGT Power MOSFET

**Table 3. Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>On/Off States</b>						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	80			V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=80V, V_{GS}=0V$			1	$\mu A$
$I_{GSS}$	Gate-Body Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$			$\pm 100$	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	2		4	V
$g_{FS}$	Forward Transconductance	$V_{DS}=10V, I_D=20A$		25		S
$R_{DS(ON)}$	Drain-Source On-State Resistance	$V_{GS}=10V, I_D=20A$		4.7	6.1	m $\Omega$
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=40V, V_{GS}=0V,$ $f=1.0MHz$		3560		pF
$C_{oss}$	Output Capacitance			630		pF
$C_{riss}$	Reverse Transfer Capacitance			23		pF
$R_g$	Gate resistance	$V_{GS}=0V, V_{DS}=0V, f=1.0MHz$		2.3		$\Omega$
<b>Switching Parameters</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{GS}=10V, V_{DS}=40V,$ $R_L=2\Omega, R_{GEN}=3\Omega$		15		nS
$t_r$	Turn-on Rise Time			24		nS
$t_{d(off)}$	Turn-Off Delay Time			32		nS
$t_f$	Turn-Off Fall Time			13		nS
$Q_g$	Total Gate Charge	$V_{GS}=10V, V_{DS}=40V, I_D=20A$		49		nC
$Q_{gs}$	Gate-Source Charge			14		nC
$Q_{gd}$	Gate-Drain Charge			12.5		nC
<b>Source-Drain Diode Characteristics</b>						
$I_{SD}$	Source-Drain Current (Body Diode)				120	A
$V_{SD}$	Forward on Voltage (Note 3)	$V_{GS}=0V, I_S=20A$			1.2	V
$t_{rr}$	Reverse Recovery Time	$I_F=20A, dI/dt=500A/\mu s$		57		ns
$Q_{rr}$	Reverse Recovery Charge	$I_F=20A, dI/dt=500A/\mu s$		92		nC

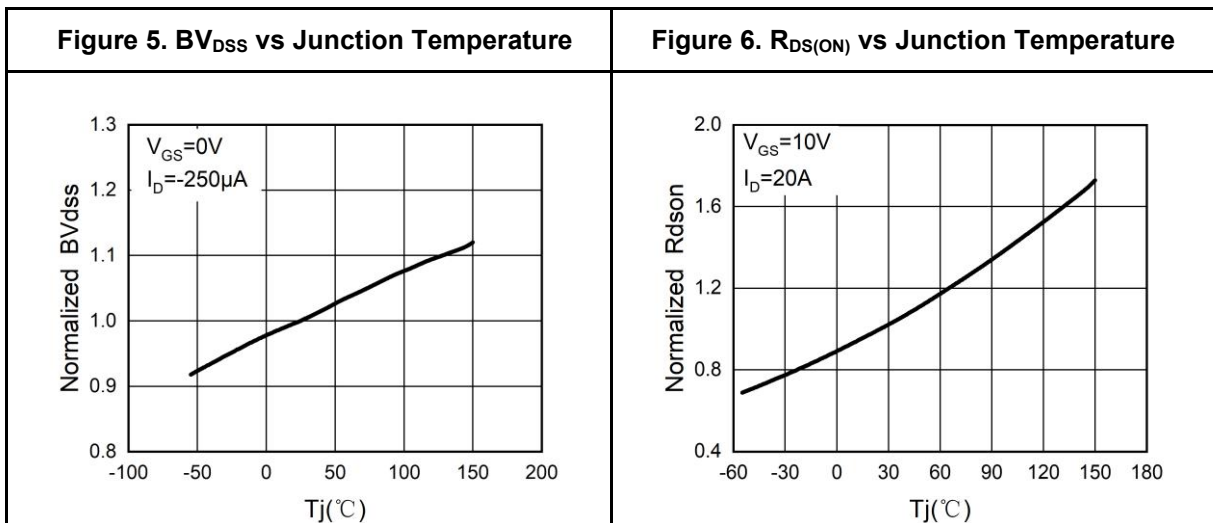
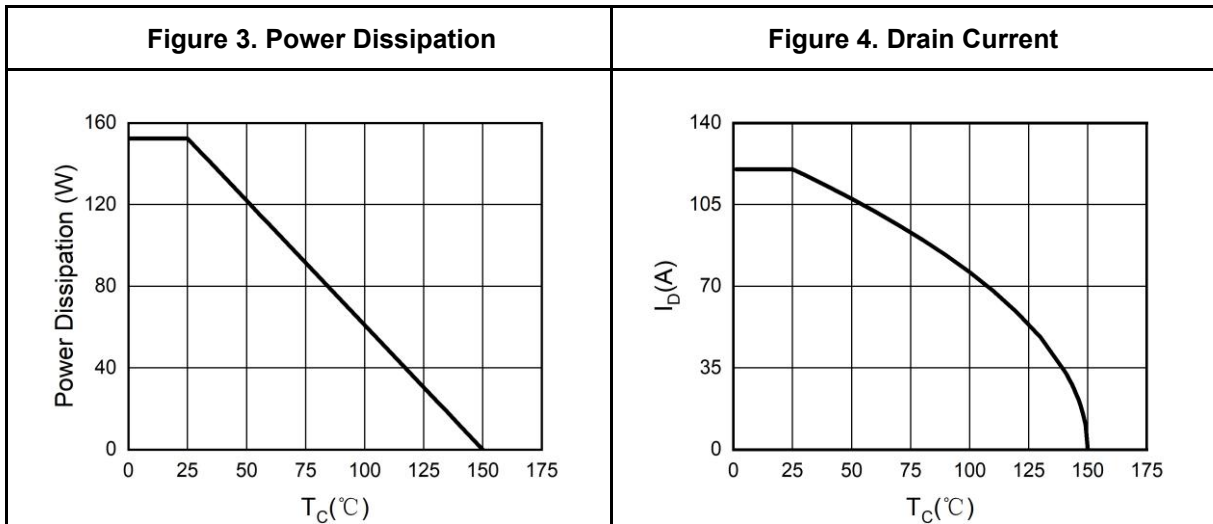
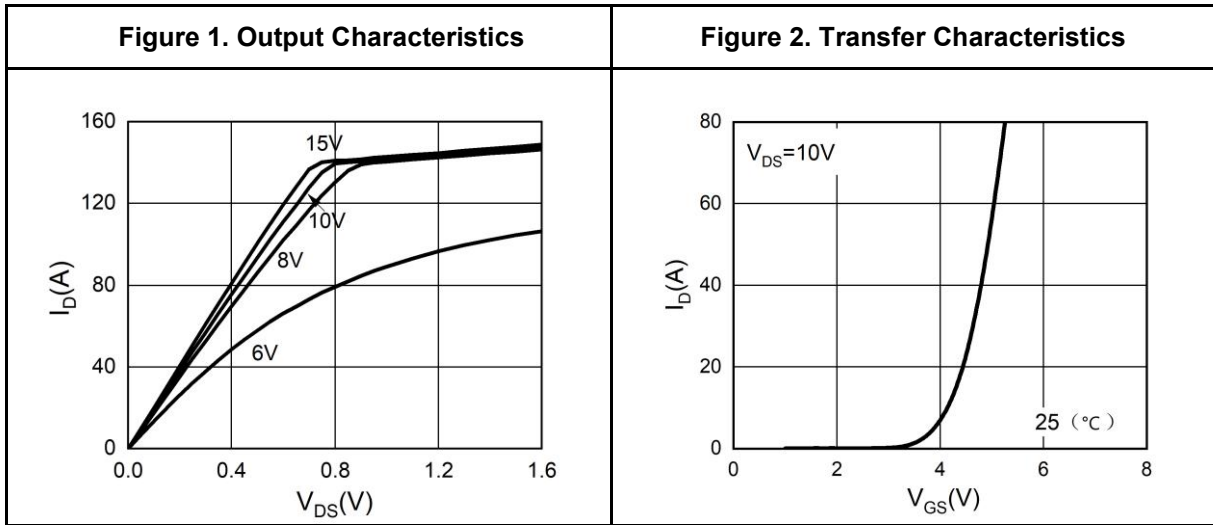
Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

Notes 2.EAS condition:  $T_J=25^\circ\text{C}, V_{DD}=40V, V_G=10V, R_g=25\Omega, L=0.5mH$ .

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.

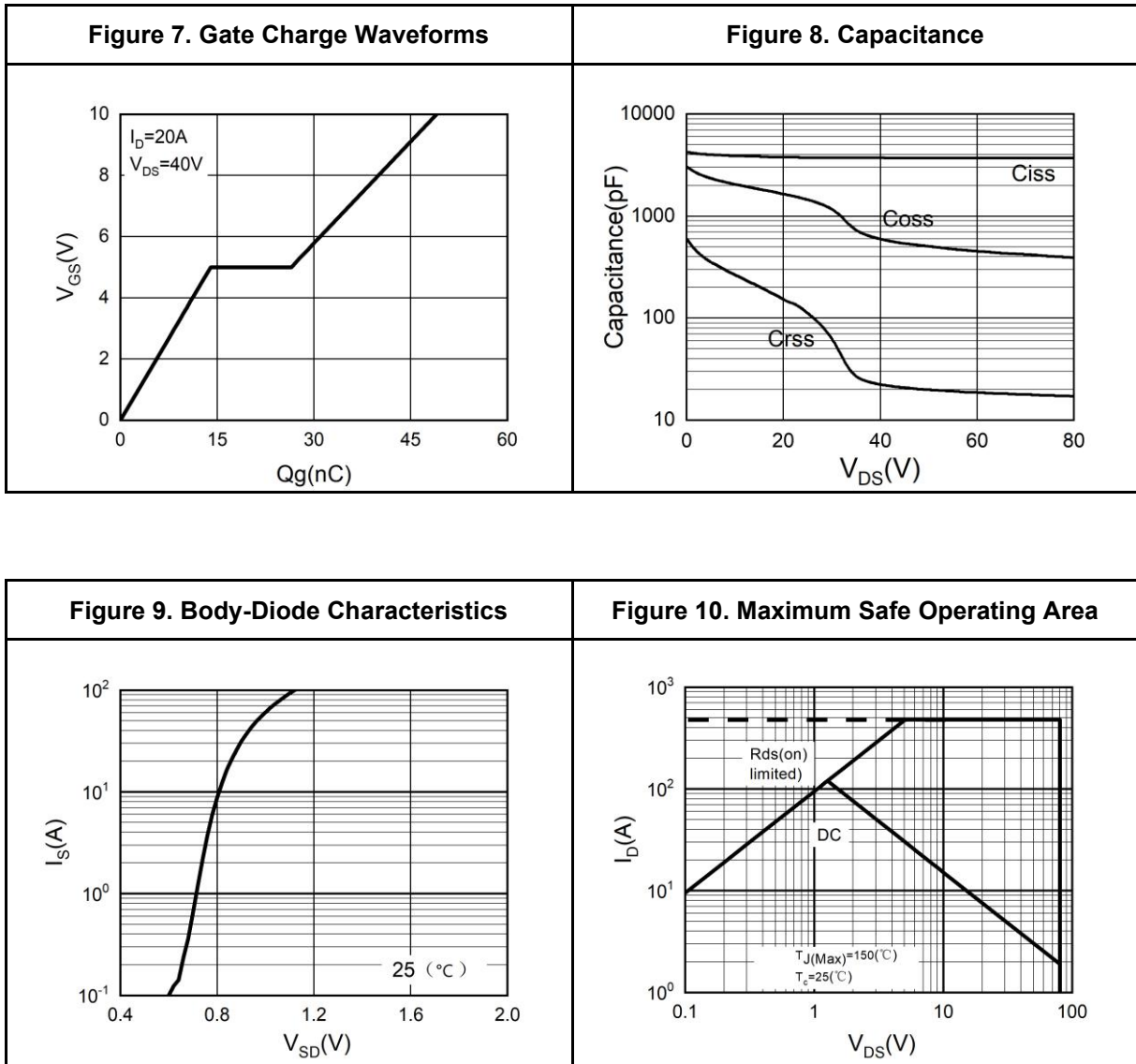


Typical Electrical And Thermal Characteristics (Curves)



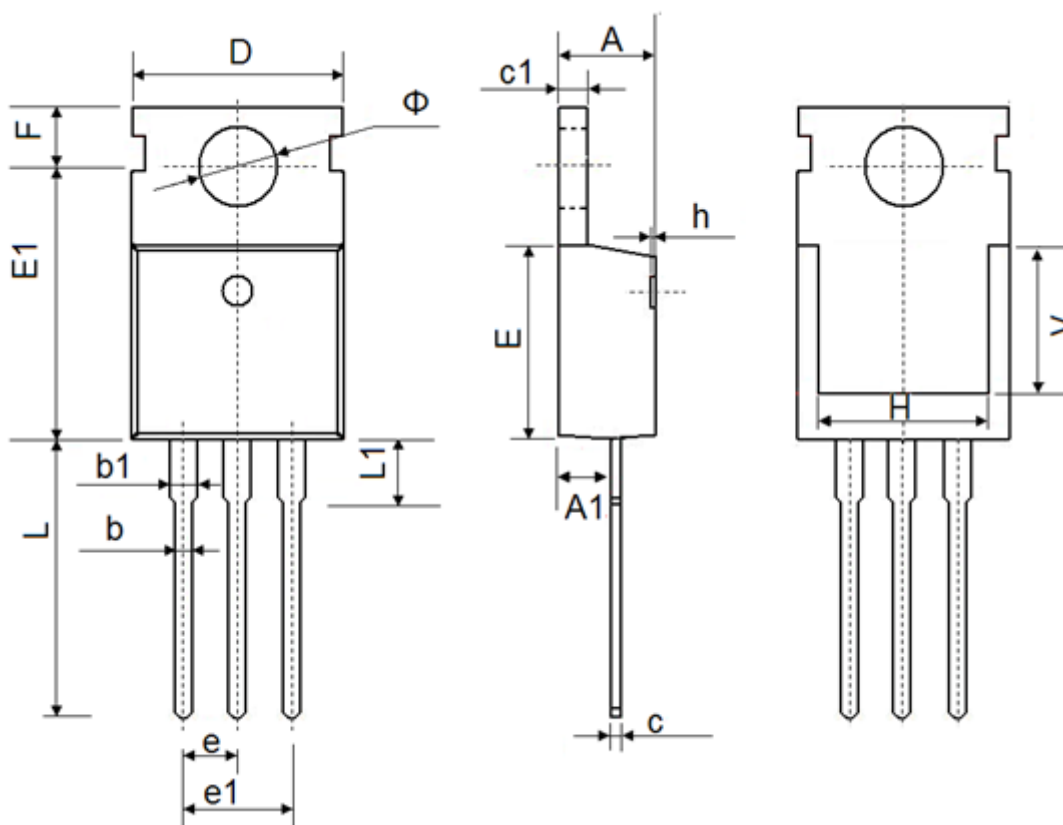


Typical Electrical And Thermal Characteristics (Curves)





TO-220 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	4.300	4.700	0.169	0.185
A1	2.200	2.600	0.087	0.102
b	0.700	0.950	0.028	0.037
b1	1.170	1.410	0.046	0.056
c	0.450	0.650	0.018	0.026
c1	1.200	1.400	0.047	0.055
D	9.600	10.400	0.378	0.409
E	8.8500	9.750	0.348	0.384
E1	12.650	12.950	0.498	0.510
e	2.540 TYP.		0.100TYP.	
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
H	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.750	14.300	0.502	0.563
L1	2.850	3.950	0.112	0.156
V	7.500 REF.		0.295 REF.	
Φ	3.400	4.000	0.134	0.157



## Attention

This product described in this document can not be used in life support devices or systems, aircraft's control systems, and other applications whose failure can be reasonably expected to result in serious physical and/or material damage, apart from that when an application agreement is signed between customer and Wuxi Shangjia Semiconductor.

The performances and characteristics of this product in the independent testing state are displayed in this document. Wuxi Shangjia Semiconductor can't guarantee of the performances and characteristics of this described product that mounted in the customer's products or equipments as same as that in the independent testing state. So the customer should evaluate and test devices mounted in the customer's products or equipments.

Wuxi Shangjia Semiconductor reserves the right to improve the designs, functions and reliability of this product and modify any and all information described in this document without notice customer, apart from that when a notice agreement is signed between customer and Wuxi Shangjia Semiconductor.

The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Wuxi Shangjia Semiconductor hereby disclaims any and all warranties and liabilities of any kind, including without limitation, warranties of non-infringement of intellectual property rights of any third party.